

RTD Series Multi-wire Saw

Ideal for Low to Medium Volume Production House or R&D Facility



FEATURES

- Processes Ingots up to 200mm diameter and 225mm long with as many as 300 slices at a time
- Minimally destructive, low-kerf slicing with diamond wire increases yield by saving material
- Simple, robust design minimizes maintenance costs and reduces downtime
- Operator-friendly 15", Color Touchscreen allows for simple programming of recipes and ease of use
- Tangential cutting method for increased surface finish quality and decreased cut time
- PLC controlled tensioning system with load cell feedback for accurate wire tension required for different wire sizes
- Smallest footprint available in a multi-wire saw (1.3 m²)
- Multiple wire break detection systems minimizes material loss due to wire breaks
- CE compliant

TECHNICAL

SPECIFICATION	RTD6400	RTD 6800
Workpiece Dimensions	150 mm L x 100 mm W x 200 mm H	150 mm L x 200 mm W x 200 mm H
Loading Length	150 mm - 225 mm (with extended web option)	
Workpiece Weight (Max)	180 Kg	
Yoke Speed (mm/min)	.0005 mm/s 1.5 mm/s	
Power Requirements	30 amp, 3-phase, 220 volt, 50/60 Hz	
Compressed Air	Pressure: 207 kPa (80 psi) Volume: 0.14 m ³ /min (5 cfm)	
Cutting Fluid Tank Capacity	110 L	

RTD SERIES OPTIONS

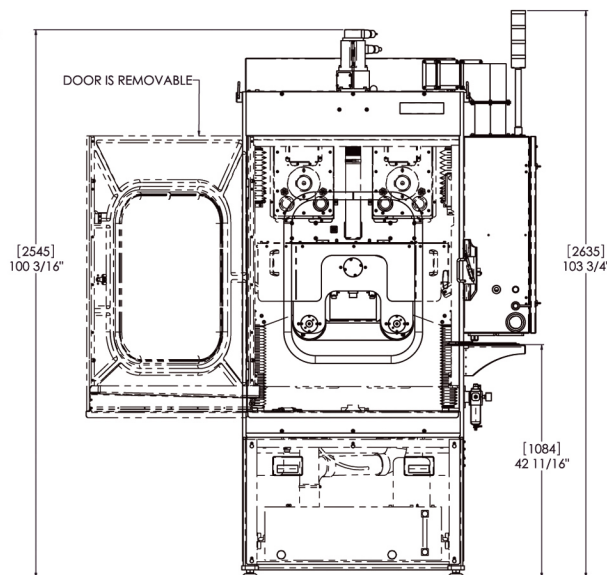
- Extended web option, extends web to 225mm (pitch dependent)
- Filtering via filter skid is available
- Precision table with two dovetails, eases mounting of the sample and maintains proper orientation
- Remote set-up and monitoring software via Ethernet
- Ingot-Mounting Station, a stand-alone unit, allows precise mounting of sample to sacrificial beam and dovetail to simplify and reduce set-up time
- Development and design consultation/custom fixturing
- Accumount Dovetail Mounting System for improved accuracy
- Manual 90° dicing table
- Automated Tilt and Rotation Table available for angular alignment

BENEFITS

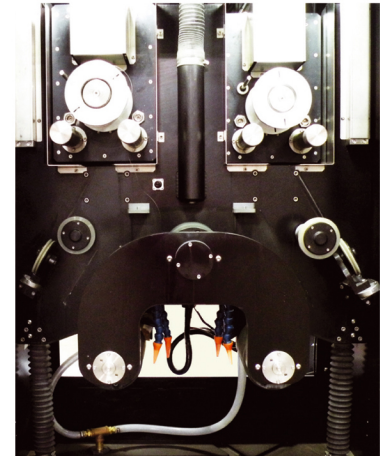
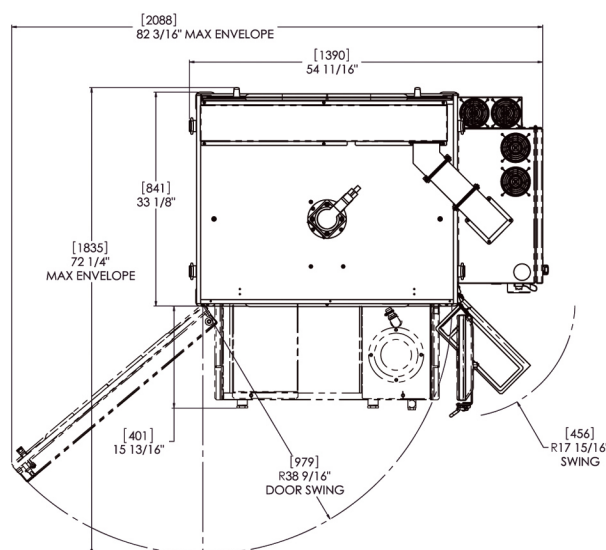
- Ideal for cutting hard and brittle materials such as: silicon, silicon carbide, quartz, fused silicon glass, ceramics, graphite, sapphire, germanium, etc.
- Increased working speed over conventional slurry process
- Adaptable design allows for many different process types from single-wire cropping to multi-wire slicing
- Efficient wire usage - increases cutting speed and enables wire changes in minutes
- Wire break detection is standard

FOOTPRINT RTD 6400 - 6800

Front View



Top View



TANGENTIAL CUTTING

- 0 - 6° rock
- Faster cuts
- Higher precision
- Lower TTV
- Superb surface finish
- Reduced bow and warp

